

# **AVS-Aware Power-Gate Sizing for Maximum Performance and Power Efficiency of Power- Constrained Processors**

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# Outline

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- Introduction
- Impact of process variations and PG-device size
  - ⊙ Impact on  $VV_{DD}$
  - ⊙ Impact on  $F_{MAX}$  and  $P_{TOT}$
- AVS-aware PG-device size optimization
  - ⊙ Algorithm and simulation result
- Impact of WID variation on PG sizing
  - ⊙ Global clocking
  - ⊙ Frequency island clocking
- Experimental methodology
- Conclusion

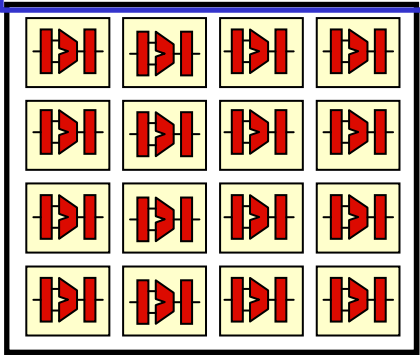
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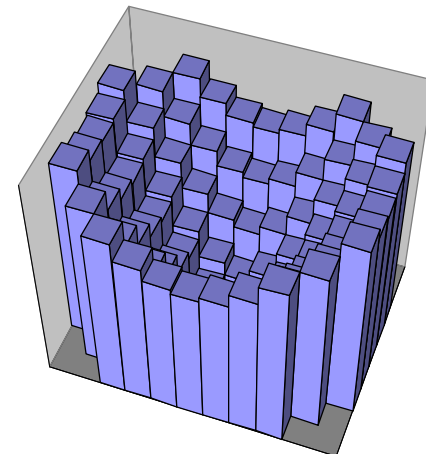
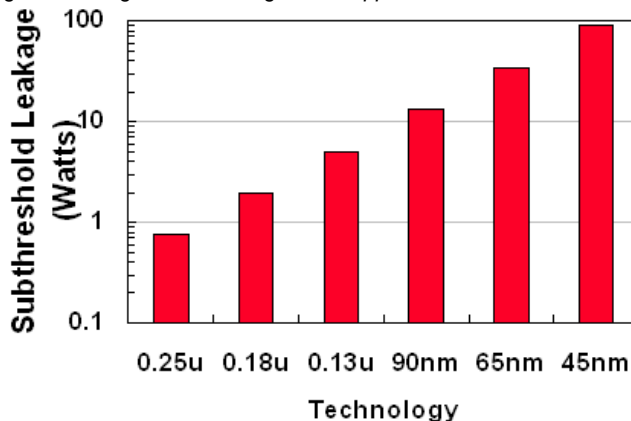
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# Introduction

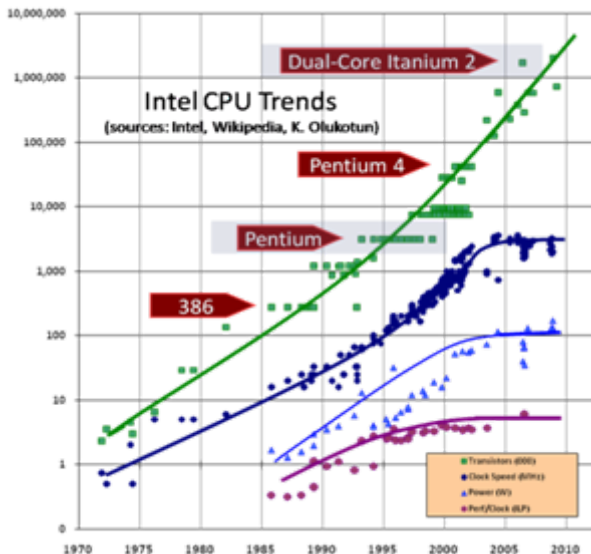
Parallel processing with multiple cores



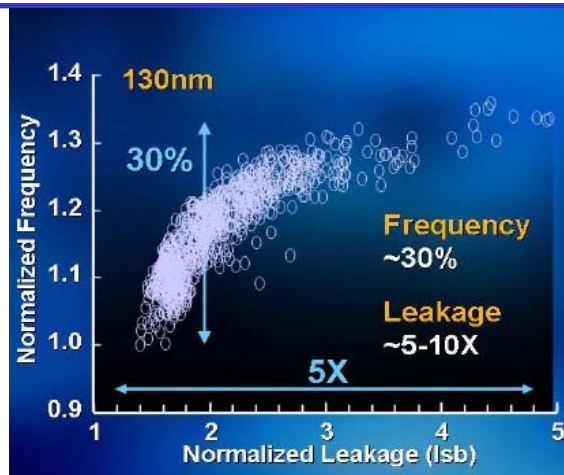
"Gigascale Integration Challenges and Opportunities", Shekhar Borkar, Intel



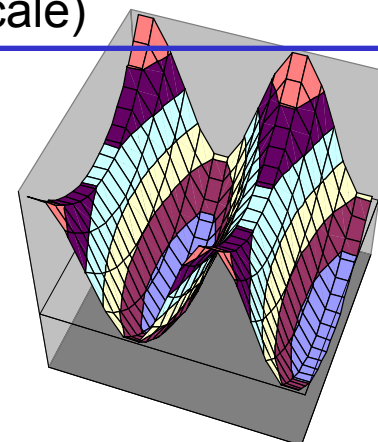
Die to Die Variation (Wafer scale)



$P_{LKG}$  increasing fraction of  $P_{TOT}$  with technology.



Intel



Within Die Variation (Die scale)

Performance and Power : increasing with technology scaling

# Contributions

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- Analyze the impact of D2D variations on
  - ⊙ Virtual rail voltage ( $V_{DD}$ )
  - ⊙ Maximum operating frequency ( $F_{MAX}$ )
  - ⊙ Total power consumption ( $P_{TOT}$ )
- Propose algorithm to find
  - ⊙ Optimal PG size
  - ⊙ Optimal degree of AVS
- Extend algorithm to
  - ⊙ Multicore processors w/ WID variation
    - Global clocking
    - Frequency Island clocking

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# Process Variation Impact on $VV_{DD}$

- $VV_{DD}$  follows load line

$$VV_{DD} = V_{DD} - R_{PG} \times I_{TOT}(VV_{DD})$$

- Fast Die

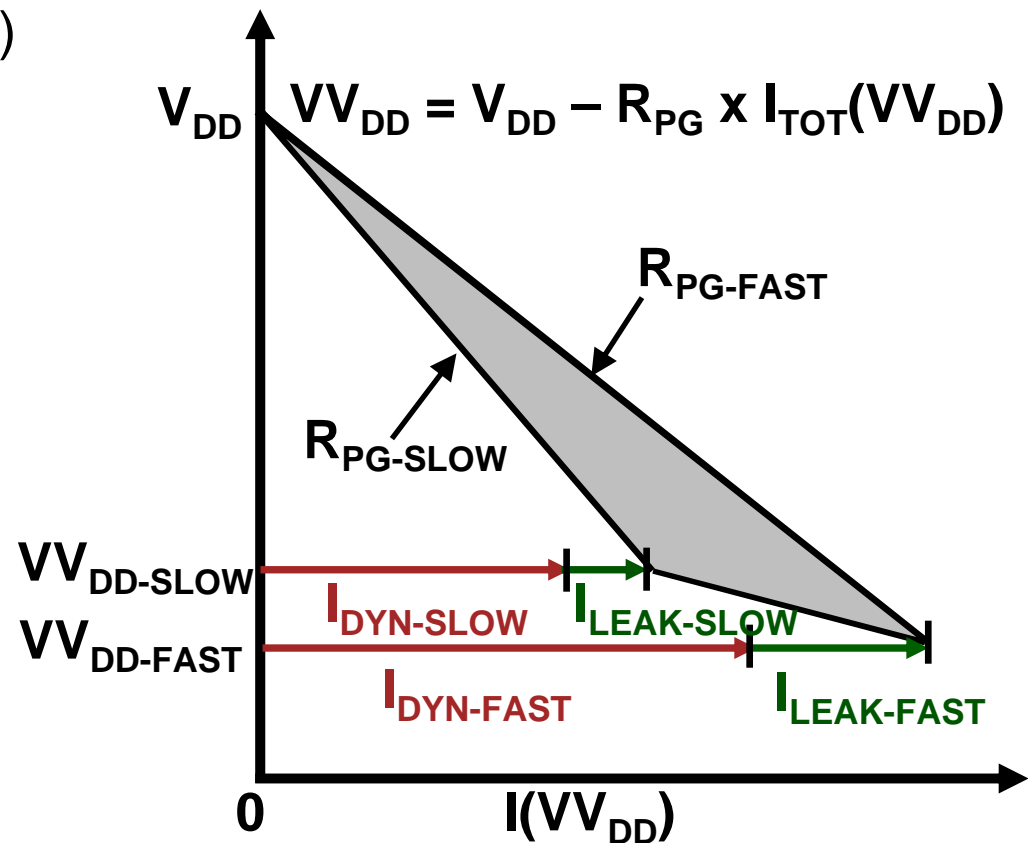
- More  $I_{TOT} \rightarrow$  Lower  $VV_{DD}$

- Slow Die

- Less  $I_{TOT} \rightarrow$  Higher  $VV_{DD}$

- Additionally

- $R_{PG-SLOW} > R_{PG-FAST}$

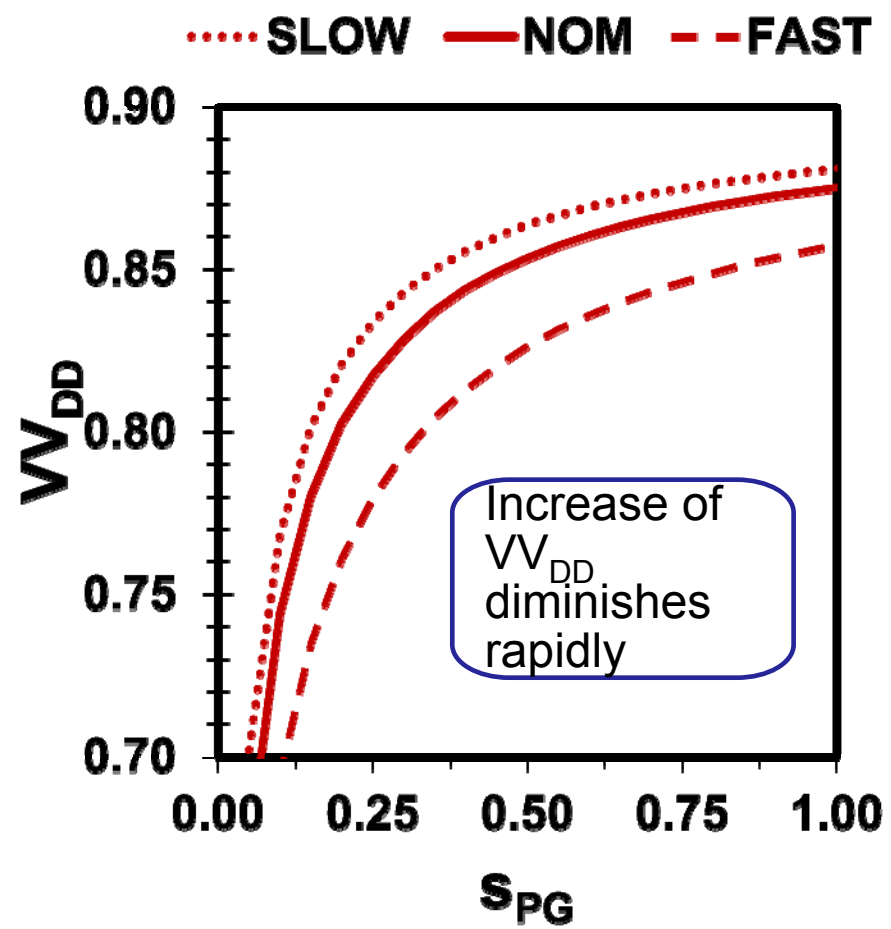
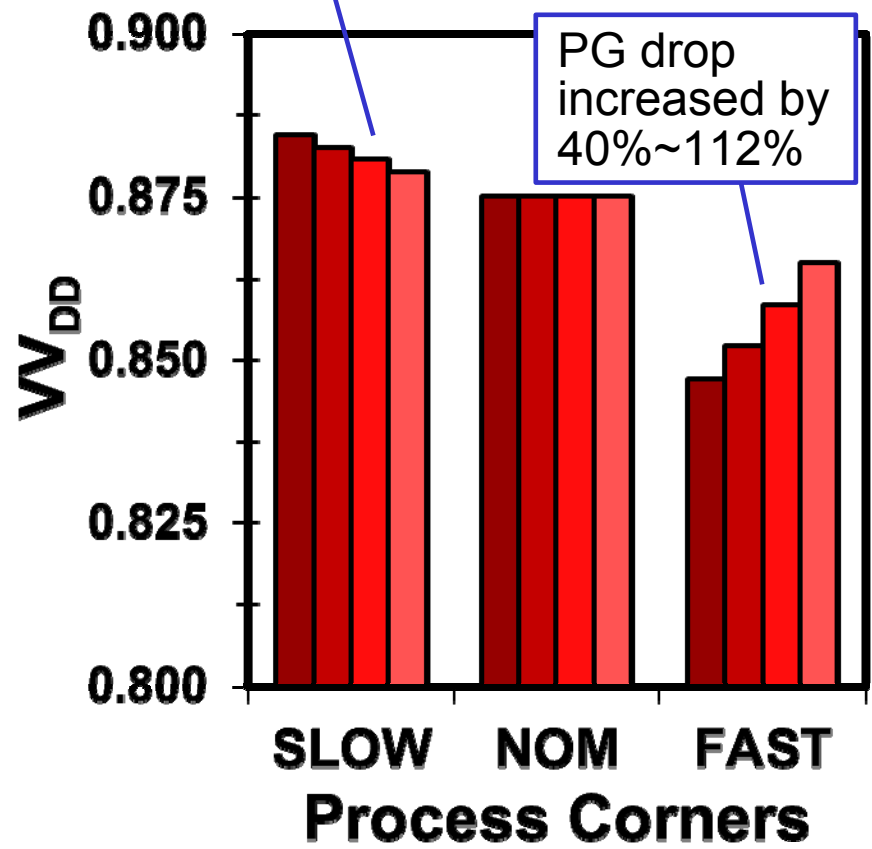


# P. V. + PG Size Impact on $VV_{DD}$

PG drop reduced by 15%~37%

NOM  $I_{LEAK}$  % = ■ 40 ■ 30 ■ 20 ■ 10

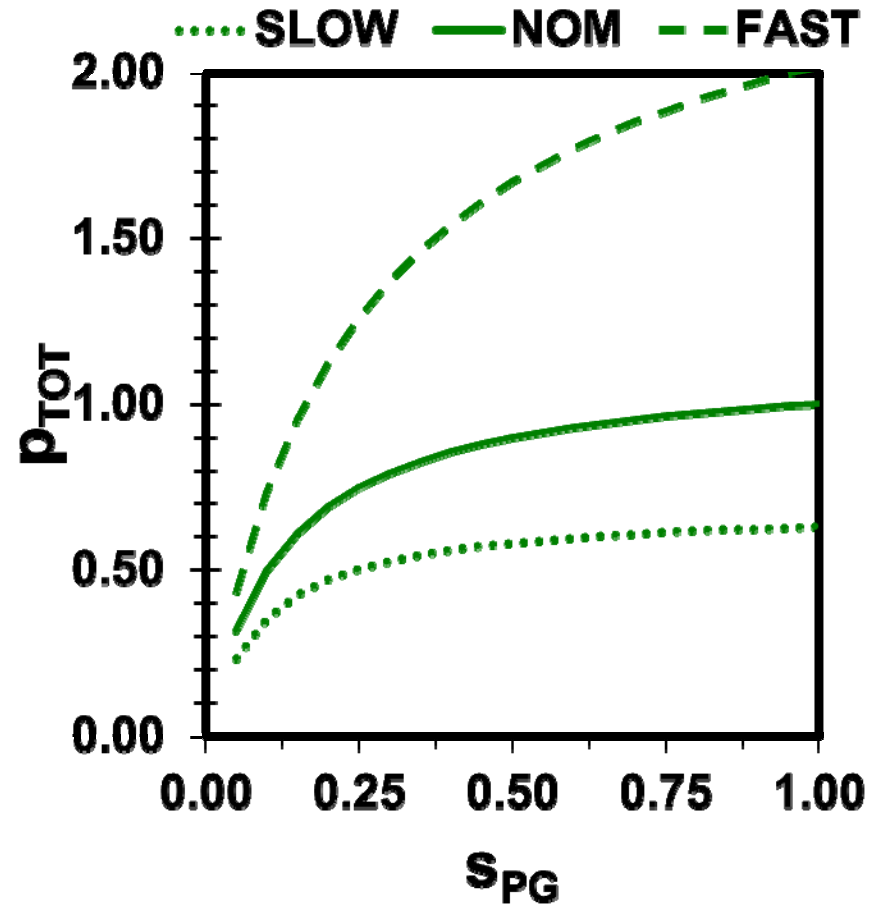
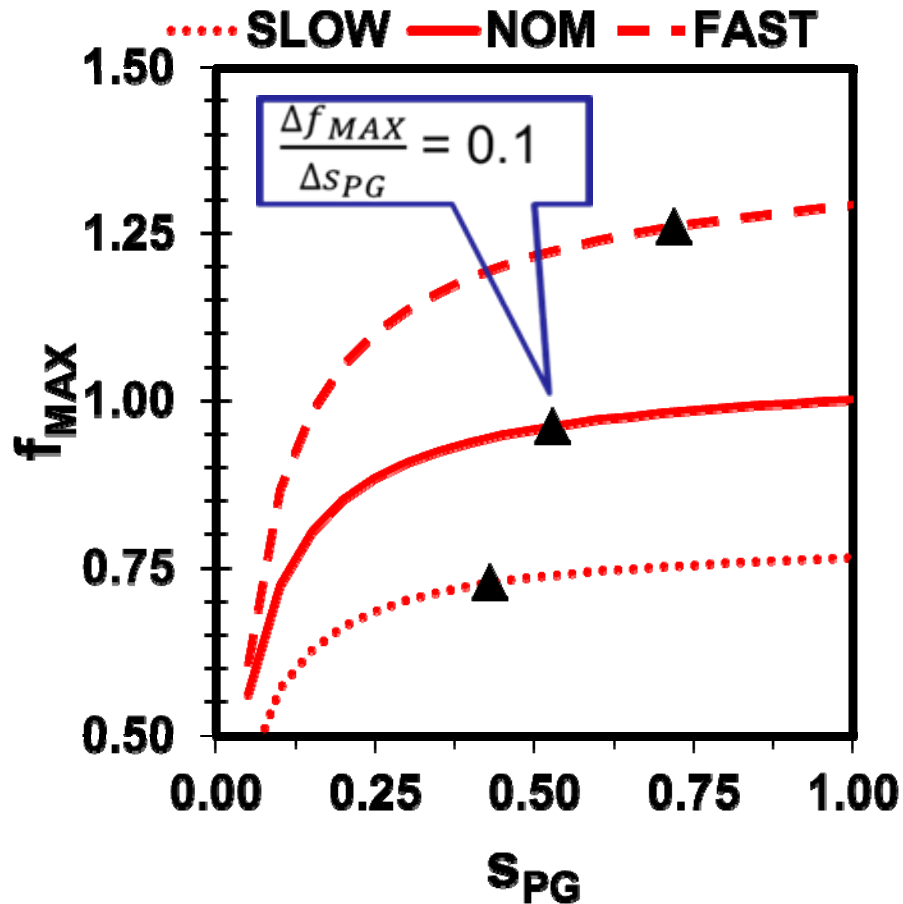
PG drop increased by 40%~112%



$s_{PG}$  increases  $\rightarrow R_{PG}$  decreases  $\rightarrow VV_{DD}$  increases



# P. V. + PG Size Impact on $F_{MAX}$ & $P_{TOT}$



- $F_{MAX}$  increase diminishes rapidly
- $P$  increases faster than  $F_{MAX}$
- Larger PG device suitable for fast die, smaller for slow die

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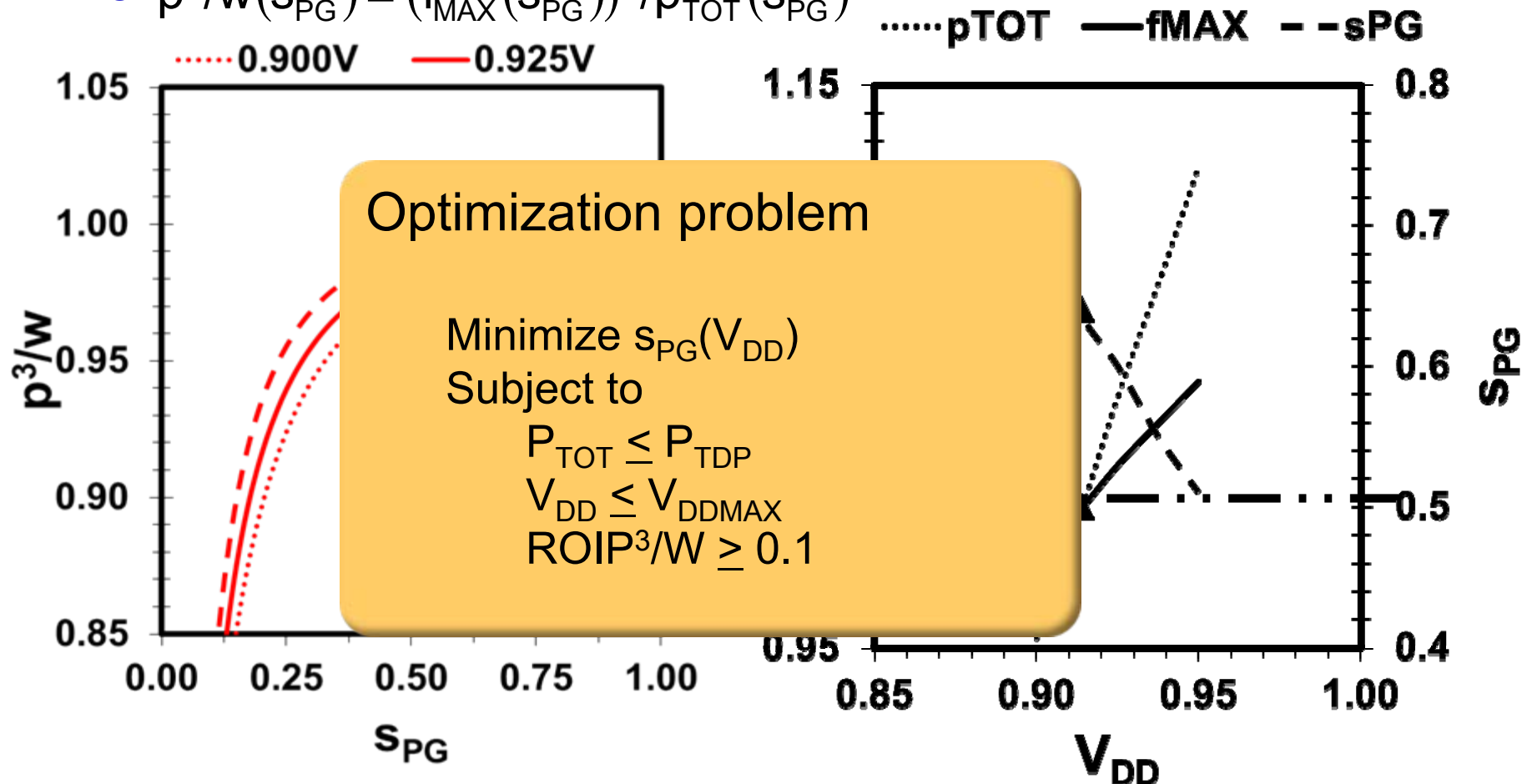
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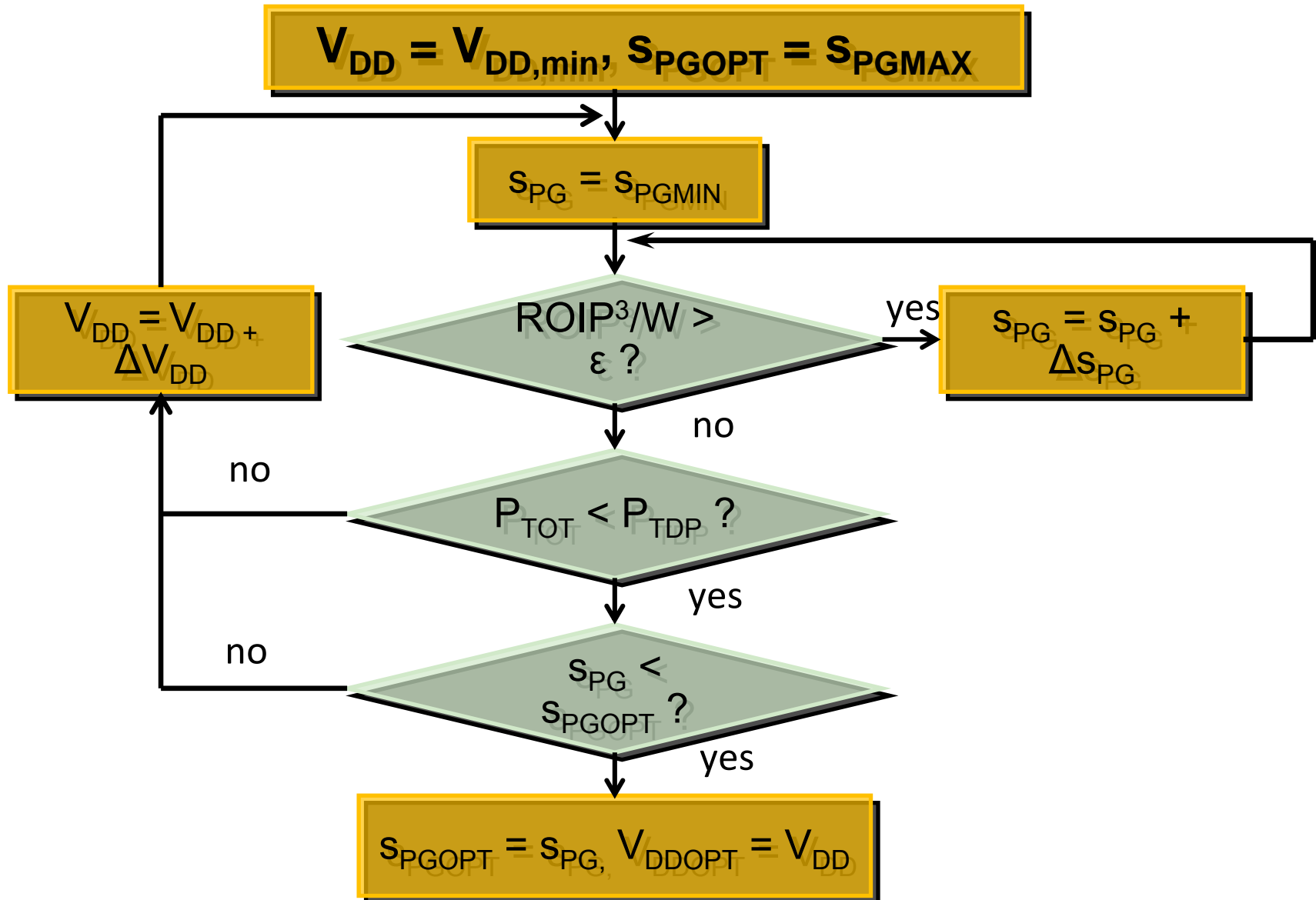
# AVS Aware PG Size Optimization

- PG size and  $V_{DD}$  both control  $F_{MAX}$  and  $P_{TOT}$
- ROIP<sup>3</sup>/W (Rate Of Increase of Performance<sup>3</sup>-per-Watt(p<sup>3</sup>/w):

$$\odot p^3/w(s_{PG}) = (f_{MAX}(s_{PG}))^3 / p_{TOT}(s_{PG})$$



# Algorithm



# Simulation Result

Proc. Corners	Slow		Nom		Fast	
$P_{TDP}$	65W	70W	90W	100W	120W	130W
$V_{DD} @ s_{PG}=1$	0.945	0.955	0.900	0.923	0.825	0.840
$s_{PGOPT}$	0.755	0.715	0.640	0.515	0.568	0.455
$V_{DDOPT}$	0.955	0.975	0.915	0.948	0.845	0.875
$f_{MAX}$	0.999	0.999	0.999	~1.000	~1.000	~1.000

- 24.5%, 36% and 43.2% reduction in PG size for slow, nominal and fast corners

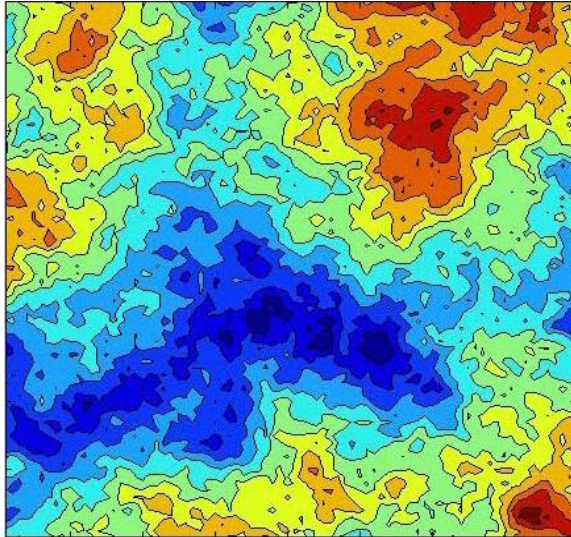
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# WID Variation

Systematic L variation



Normalized  $f(V_{DD}), I(V_{DD})$

1.03	1.06	1.01	1.00
1.15	1.38	1.04	1.00
LLC		LLC	
1.04	1.08	1.01	1.01
1.20	1.54	1.20	1.29
1.05	1.11	1.12	1.08
1.61	1.82	1.80	1.44
LLC		LLC	
1.07	1.05	1.05	1.00
1.58	1.38	1.27	1.14

82%  
Leakier

12%  
Faster

S. Sarangi et al. IEEE Trans. On Semiconductor Manufacturing, vol. 21, no. 1, pp. 3~13, Feb. 2008.

- WID spatially correlated
- Result in C2C  $F_{MAX}$  and  $I_{LEAK}$  variation
- As # of cores increases
  - Relative variation among cores more significant

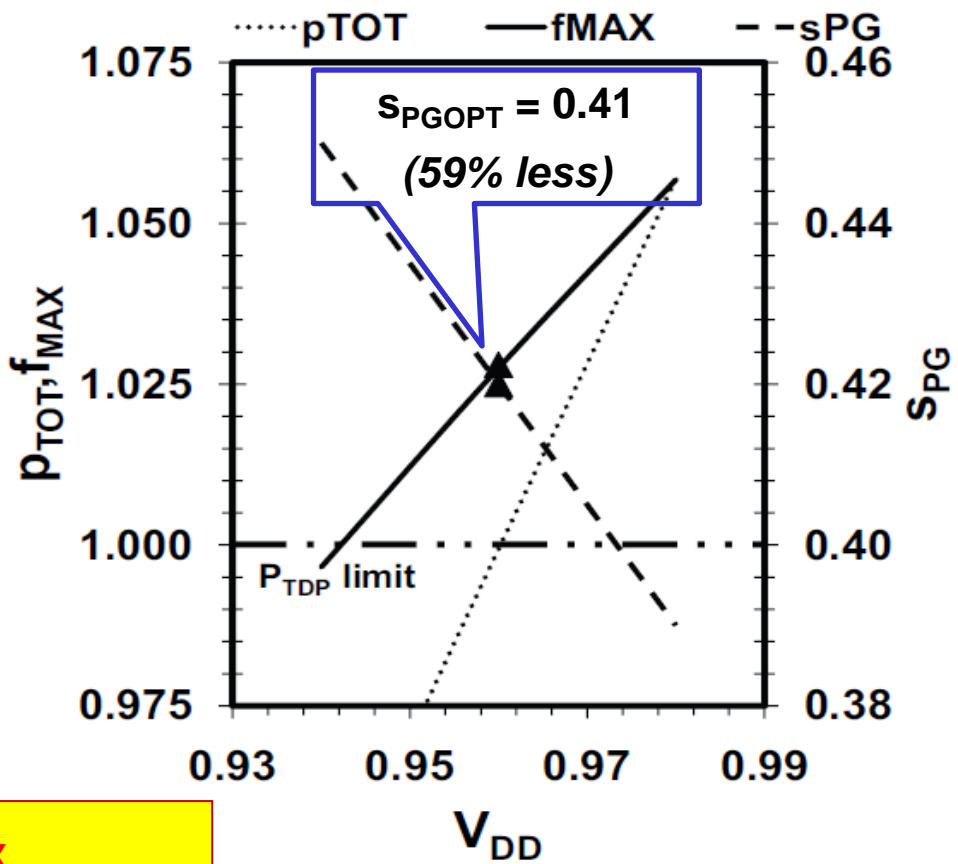
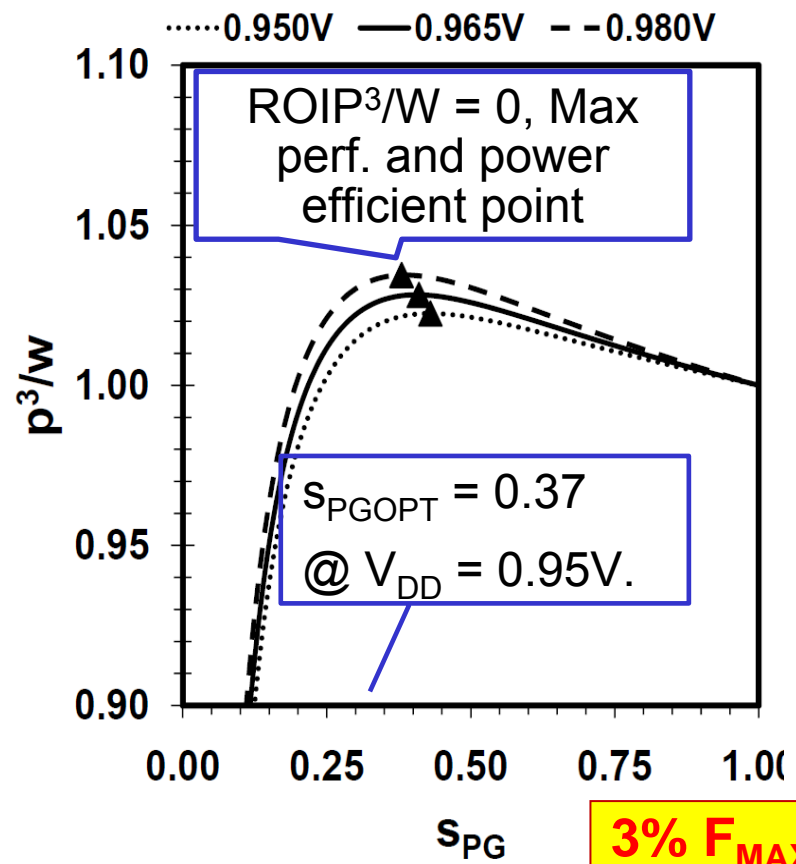
# Global Clocking

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- Limits  $F_{MAX}$  of multicore processor to that of slowest core
- Total power consumption of a N core processor
  - ⊙ 
$$P_{TOT} = \sum_{i=1}^N \left( F_{MAX,j}(V_{DD,i}) \times C_{EFF} \times V_{DD,i} + I_{LEAK,i}(V_{DD,i}) \right) \times V_{DD,i}$$
  - ⊙ where N = no. of cores  
 j = index of slowest core on die  
 $C_{eff}$  = effective switched capacitance per core



# Global Clocking



**3% F<sub>MAX</sub> improvement**

As PG size increases, faster(leakier) cores increase I<sub>LEAK</sub>, F<sub>MAX</sub> is fixed by slowest core.

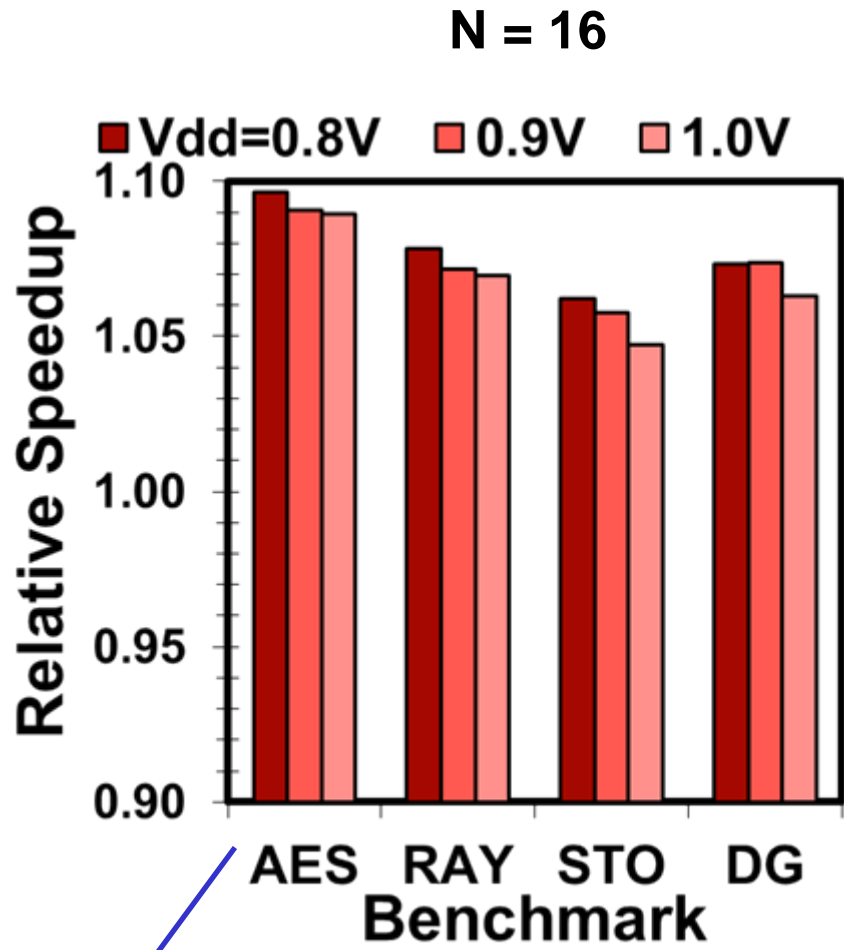
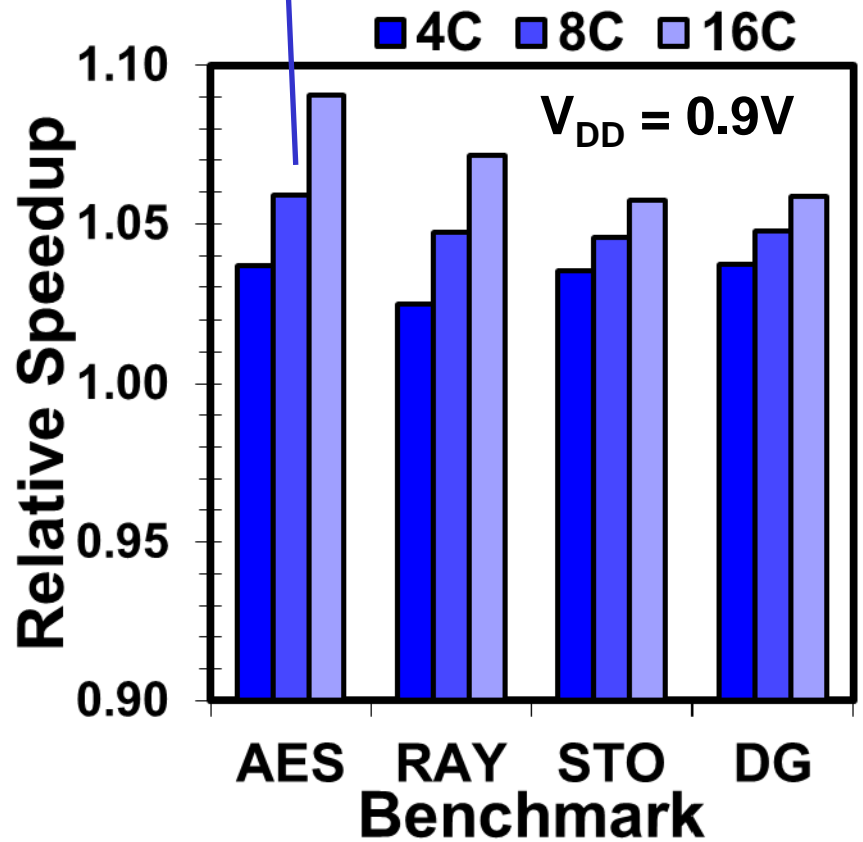
# Frequency Island Clocking

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- Each core runs at its own max. frequency
- Total power consumption of a N core processor
  - ⊙  $P_{\text{TOT}} = \sum_{i=1}^N (F_{\text{MAX},i}(V_{\text{DD},i}) \times C_{\text{EFF}} \times V_{\text{DD},i} + I_{\text{LEAK},i}(V_{\text{DD},i})) \times V_{\text{DD},i}$
- For compute-bound workloads with sufficient # of threads
  - ⊙ Performance(Throughput) =  $\left[ \sum_1^N F_{\text{MAX},i} \right] / N$

# Throughput Experiment with FI Clk.

As # of cores increases, C2C  $F_{MAX}$  variations increase leading to higher  $F_{MAX,avg}$



Compute bound workloads with large # of threads, future RMS applications

*Speedup degrades as V<sub>DD</sub> (thus F<sub>MAX,avg</sub>) increases due to limited main memory resource*

# PG Sizing with FI clocking and WID Var.

- As #. of cores/die  $\uparrow$

- $V_{DDOPT} \downarrow$

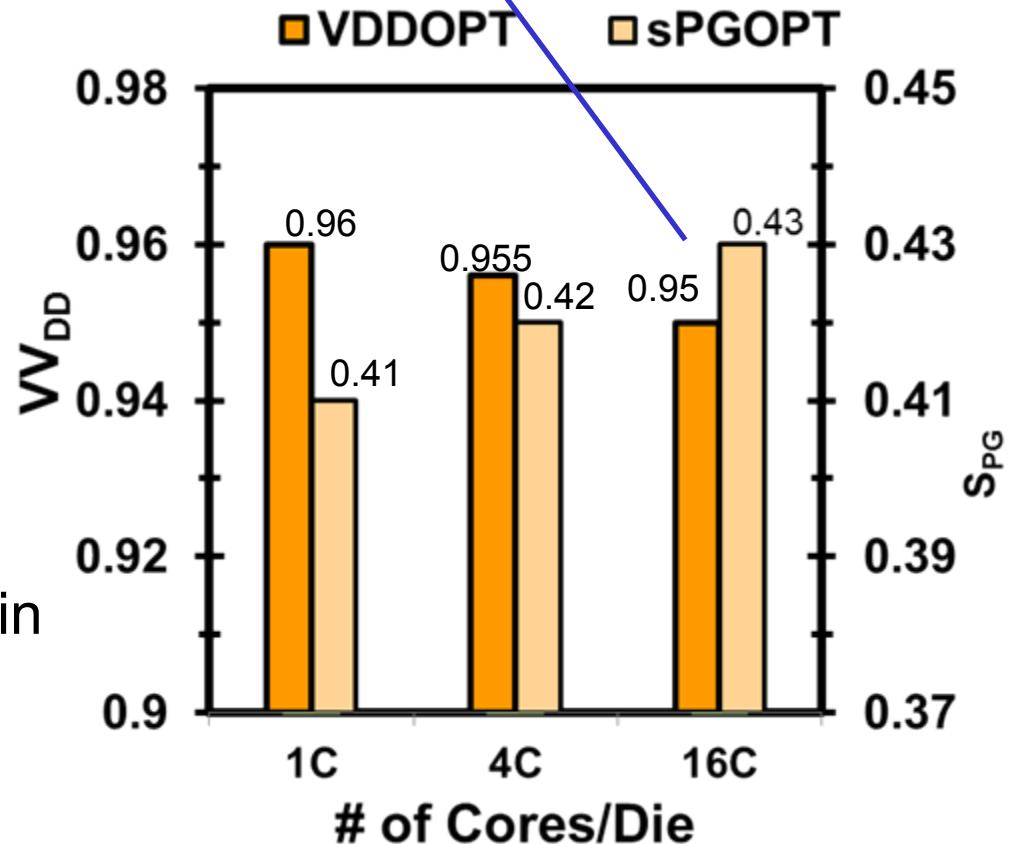
- $S_{PGOPT} \uparrow$

$F_{MAX,AVG}$  improved by ~3%

$ROIP^3/W = 0$

- In FI clocking faster (and leakier) cores increase  $F_{MAX,AVG}$

- Larger PG increases  $I_{LEAK}$  in fast cores; so  $V_{DDOPT}$  must reduce to satisfy  $P_{TDP}$



Use  $F_{MAX,AVG}$  to compute  $P^3/W$  constraint

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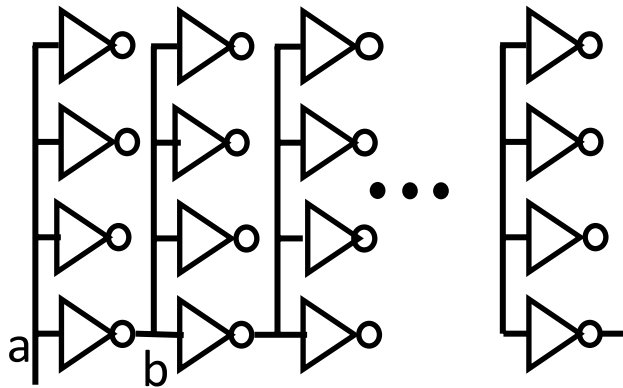
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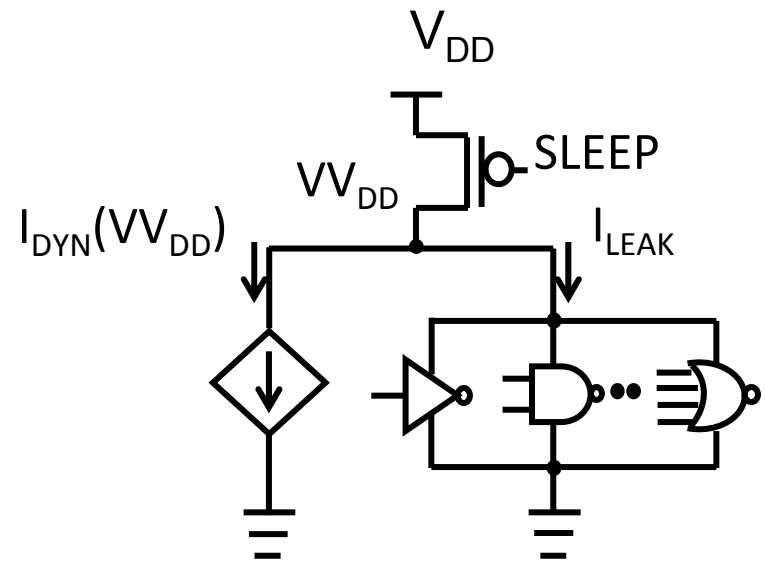
# Experimental Methodology

- For frequency and leakage modeling with power gates

- $V_{th}$  and  $L_{eff}$  WID spatial and D2D variation map\*
  - WID variation : Correlation coefficient = 0.5
  - D2D variation :  $\sigma_{V_{th}}^{sys} = 6.4\%$



24 FO4 INV chain for measuring  $f(V_{DD})$   
32nm PTM SPICE model



Dummy gates for measuring  $I(V_{DD})$

*Effective Widths*

50% INV, 30% NAND, 20% NOR

# Experimental Methodology

- Power and thermal constraint
  - $P_{TDP}$  at  $V_{DD,TDP} = 90$  W (at the nominal corner)
  - $T_{jmax} = 100$  ° C
- Performance simulation with GPGPU-Sim
  - Simulator modified to support FI clocking

# of SM Cores	4/8/16	Shared Mem/SM	16KB
SIMD Width/SM	1/4/8	# of Mem Ch.	4
# of Threads /SM	1024	BW/ Mem Ch.	8B/Cycle
3 of CTAs/SM	8	DRAM Rq. Queue	16
# of Registers/SM	16384	Mem Controller	FR-FCFS
Constant and Texture Cache Sizes	8KB, 2-Way, 64B Line	GDDR3 Mem# of SM Cores . tCL/tRP/tRAS	10/10/35/25

# Conclusion

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- Effect of PG-device sizing on  $F_{MAX}$  and  $P_{TOT}$ 
  - ⊙  $F_{MAX}$  and  $P_{TOT}$  both increase,  $P_{TOT}$  increases faster than  $F_{MAX}$ .
  - ⊙ Rate of increase diminishes quickly for slow die than for fast die
- Reduction in PG-device size
  - ⊙ D2D variation :
    - 24.5%(slow), 36%(nominal) and 43.2%(fast)
  - ⊙ WID variation
    - Global Clk. **59%**
    - FI Clk. **58%** (4 cores), **57%** (16 cores)
- $F_{MAX}$  penalty
  - ⊙ D2D variation : negligible
  - ⊙ WID variation : improved  $F_{MAX}$  by ~3%
- As #. of cores increases
  - ⊙ Opt. PG size increases
  - ⊙ Opt.  $V_{DD}$  for AVS decreases